

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-58. (cancelled)

59. (new) An intercoupling component for receiving an array of contacts within a digital or analog transmission system having an electrical ground circuit and a chassis ground circuit, the intercoupling component comprising:

a substrate formed of electrically insulative material and having an upper surface, the substrate including a plurality of holes disposed on its upper surface and arranged in a predetermined footprint corresponding to the array of a contacts; and

a plurality of electrically conductive signal contacts configured to transmit a digital or analog communication signal, each signal contact disposed within a hole on the upper surface of the substrate forming an array of signal contacts,

wherein some or all of the electrically conductive signal contacts are surrounded by an electrically conductive member configured to electrically connect to the chassis ground circuit.

60. (new) The intercoupling component of claim 59 wherein the electrically conductive member comprises a frame formed around an outer perimeter of the substrate.

61. (new) The intercoupling component of claim 59 wherein the electrically conductive member comprises a shield at least partially disposed within the substrate.

62. (new) The intercoupling component of claim 59, further comprising:

a plurality of electrically conductive reference contacts each disposed within a hole on the upper surface of the substrate, wherein the electrically conductive reference contacts are configured to electrically connect to the reference ground circuit of the system.

63. (new) The intercoupling component of claim 59 wherein the substrate comprises a plurality of segments formed of electrically conductive material.

64. (new) The intercoupling component of claim 59 wherein the plurality of signal contacts are configured to transmit single-ended signals.

65. (new) The intercoupling component of claim 59 wherein the plurality of signal contacts are configured to transmit differential signals.

66. (new) An intercoupling component for receiving an array of contacts within a digital or analog transmission system having an electrical ground circuit and a chassis ground circuit, the intercoupling component comprising:

an array of electrically conductive contacts disposed in a substrate formed of electrically insulative material; and

an electrically conductive shield at least partially disposed within the array of electrically conductive contacts, wherein the shield is configured to electrically connect with the chassis ground circuit.

67. (new) The intercoupling component of claim 66 wherein the shield surrounds a portion of the contacts within the array of contacts.

68. (new) The intercoupling component of claim 66 further comprising:  
a frame disposed around the array of contacts and configured to electrically connect with the chassis ground circuit.

69. (new) The intercoupling component of claim 68 wherein the frame is electrically connected to the shield.

70. (new) The intercoupling component of claim 69 wherein the frame and the shield are a single piece construction.

71. (new) The intercoupling component of claim 66 wherein the array of contacts are configured to transmit differential signals.

72. (new) The intercoupling component of claim 66 wherein the array of contacts are configured to transmit single ended signals.

73. (new) The intercoupling component of claim 66 further comprising:  
one or more members electrically connected to the electrical ground circuit disposed within the array of contacts.

74. (new) The intercoupling component of claim 73 wherein the members comprise contacts.

75. (new) The intercoupling component of claim 73 wherein the members comprise ground planes.

76. (new) An intercoupling component for receiving an array of contacts within a digital or analog transmission system having an electrical ground circuit and a chassis ground circuit, the intercoupling component comprising:

an array of electrically conductive contacts disposed in a substrate formed of electrically insulative material; and

an electrically conductive frame disposed around the array of electrically conductive contacts, wherein the frame is configured to electrically connect with the chassis ground circuit.

77. (new) The intercoupling component of claim 76 further comprising:  
one or more shield members, each member at least partially disposed within the array of contacts and configured to electrically connect with the chassis ground circuit.

78. (new) The intercoupling component of claim 76 wherein the array of contacts are configured to transmit differential signals.

79. (new) An apparatus for use in a digital or analog transmission system having an electrical ground circuit and a chassis ground circuit, the circuit card comprising:  
a printed circuit board; and  
an interconnection device coupled to the printed circuit board, the interconnection device comprising:

an array of electrically conductive contacts disposed in a substrate formed of non-conductive material; and

an electrically conductive member at least partially disposed within the array of electrically conductive contacts, wherein the shield is configured to electrically connect with the chassis ground circuit.

80. (new) The apparatus of claim 79 wherein the electrically conductive member comprises a shield formed of electrically conductive material.

81. (new) The apparatus of claim 79 wherein the electrically conductive member surrounds a portion of the contacts within the array of contacts.

82. (new) The apparatus of claim 80 further comprising:

a frame disposed around the array of contacts and configured to electrically connect with the chassis ground circuit.

83. (new) The apparatus of claim 82 wherein the frame is electrically connected to the shield.

84. (new) A circuit card for use in a digital or analog transmission system having an electrical ground circuit and a chassis ground circuit, the circuit card comprising:

a plurality of contact pads arranged in a predetermined footprint; and

an interconnection device comprising:

an array of electrically conductive contacts disposed in a substrate formed of non-conductive material; and

an electrically conductive frame disposed around the array of electrically conductive contacts, wherein the frame is configured to electrically connect with the chassis ground circuit.

85. (new) An method of manufacture for an interconnection device comprising:  
providing a substrate formed of non-conductive material and adapted to secure an array of contacts; and

forming a frame around the perimeter of the substrate.

86. (new) The method of claim 85 wherein the frame comprises electrically conductive material.

87. (new) The method of claim 85 wherein forming a frame comprises:  
injection molding a frame around the perimeter of the substrate.

88. (new) The method of claim 85 wherein forming a frame comprises:

injection molding a frame around the perimeter of the substrate.

89. (new) The method of claim 85 wherein the frame is configured to electrically connect with a chassis ground circuit of a digital or analog transmission system.